# Preface ICMSSM2021

We present to your attention proceedings of the 7th International Conference on Mechanical Structures and Smart Materials (ICMSSM2021), which was held virtual on June 14-15, 2021, in Changsha, China.

ICMSSM2021 aimed to bring together experts from academia and industry to present and discuss their research results and development in the areas of mechanical structures and smart materials. It provided opportunities for delegates to exchange new ideas and application experiences and to establish collaborations.

In ICMSSM 2021, Prof. Roger M. Leblanc, Prof. Peter Cochrane, Prof. Yuebing Zheng, Prof. Vladimir M. Fomin, etc., delivered the keynote or plenary speeches, which focused on the latest research nanomaterials, superconductors, smart materials and structures, etc. And in the parallel sessions, participants started the discussion related to the latest progress or researches about mechanical materials, composite materials, etc.

Finally, we would like to thank members of the conference committee and reviewers for their efforts in conference dissemination, paper reviewing, etc. We are hoping COVID-19 will be ended soon and looking forward to meeting everyone at the ICMSSM2022 conference at the site again.

With our warmest regards,
Organizing Committee
June 18, 2021

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